



SPECIFICATION

- · Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- · Samsung P/N :
- CL21B822KBANNNC

(Reference sheet)

- · Description : C
- CAP, 8.2nF, 50V, ±10%, X7R, 0805

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A. Samsung Part Number

			<u>CL</u> ①	<mark>21</mark> ②	<u>B</u> 3	<u>822</u> ④	<u>K</u> 5	<u>B</u> 6	▲ ⑦	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<u>С</u> Ш		
1	Series	Samsung Multi-layer Ceramic Capacitor													
2	Size	0805 ((inch c	ode)		L:	2.00	± 0.10	mm			W:	1.25 ± 0.10	mm	
3	Dielectric	X7R					8	Inner	elect	rode			Ni		
4	Capacitance	8.2 ו	٦F					Term	inatio	n			Cu		
5	Capacitance	±10 °	%					Platir	ıg				Sn 100%	(Pb Free)	
	tolerance						9	Prod	uct				Normal		
6	Rated Voltage	50 \	V				10	Spec	ial				Reserved for	r future use	
\bigcirc	Thickness	0.65 ± 0.7	10 mm				1	Packa	aging				Cardboard 7	Гуре, 7" reel	

B. Structure & Dimension



Samsung P/N	Dimension(mm)							
Samsung F/N	L	W	Т	BW				
CL21B822KBANNNC	2.00 ± 0.10	1.25 ± 0.10	0.65 ± 0.10	0.50 +0.2/-0.3				

C. Samsung Reliablility Test and Judgement Condition

Tan δ (DF) 0.025 max. *A capacitor prior to measuring the capacitance is heat treated at 150 °C+0/-10 °C for 1 hour and maintained in ambient air for 24±2 hours. Insulation 10,000Mohm or 500Mohm×//= Rated Voltage 60~120 sec. Resistance Whichever is smaller Appearance Microscope (×10) Withstanding No abnormal exterior appearance Microscope (×10) Withstanding No dielectric breakdown or mechanical breakdown 250% of the rated voltage Yotage mechanical breakdown 500g f, for 10±1 sec. Temperature X7R Solder shifts and the imit (1mm) Adhesive Strength No peeling shall be occur on the terminal electrode 500g f, for 10±1 sec. Bending Strength Capacitance change : within ±12.5% Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface is to be soldered newly SnAg3.0Cu.0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.) Vibration Test Capacitance change : within ±7.5% Solder pot : 270±5°C, 10±1 sec. Soldering Heat Tan δ, IR : initial spec. From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z) Wibration Test Capacitance change : within ±12.5% With rated voltage Resistance <td< th=""><th></th><th>Judgement</th><th>Test condition</th></td<>		Judgement	Test condition
Tan δ (DF)0.025 max.treated at 150°C+04-10°C for 1 hour and maintained in ambient air for 24±2 hours.Insulation10,000Mohm or 500Mohm× μ^{β} Rated Voltage60~120 sec.ResistanceWhichever is smallerMotion or south or s	Capacitance	Within specified tolerance	1 ^{kHz} ±10% / 1.0±0.2Vrms
ResistanceWhichever is smallerAppearanceNo abnormal exterior appearanceMicroscope (×10)WithstandingNo dielectric breakdown or mechanical breakdown 250% of the rated voltageVoltagemechanical breakdown or mechanical breakdown 250% of the rated voltageTemperature CharacteristicsX7R (From-55°C to 125°C, Capacitance change should be within ±15%)Adhesive Strength of TerminationNo peeling shall be occur on the terminal electrode $500g$ f, for 10±1 sec.Bending Strength of TerminationCapacitance change : within ±12.5%Bending to the limit (1mm) with 1.0mm/sec.SolderabilityMore than 75% of terminal surface is to be soldered newlySnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.)Resistance to Soldering Heat Tan δ , IR : initial spec.Solder pot : 270±5°C, 10±1sec.Wibration Test Wibration TestCapacitance change : within ±12.5% Tan δ : 0.05 max IR : 500Mohm or 25Mohm × μ^d Whichever is smallerWith 200% of the rated voltage Max. operating temperature 1000+48/-0hrsHigh Temperature ResistanceCapacitance change : within ±12.5% Tan δ : 0.05 max IR : 1,000Mohm or 50Mohm × μ^d Whichever is smallerWith 200% of the rated voltage Max. operating temperature 1000+48/-0hrsHigh Temperature Capacitance change : within ±12.5% Whichever is smallerWith 200% of the rated voltage Max. operating temperature 1000+48/-0hrsTemperature Whichever is smallerJope condition Min. operating temperature Min. operating temperature Min. operating temperature Min. operating tem	Tan δ (DF)	0.025 max.	treated at 150 $^\circ\!\!\mathrm{C}$ +0/-10 $^\circ\!\!\mathrm{C}$ for 1 hour and maintained in
AppearanceNo abnormal exterior appearanceMicroscope (×10)WithstandingNo dielectric breakdown or mechanical breakdown 250% of the rated voltageYoltagemechanical breakdown 250% of the rated voltageTemperatureX7R 250% of the rated voltageCharacteristics(From-55° to 125°C, Capacitance change should be within ±15%)Adhesive StrengthNo peeling shall be occur on the terminal electrode $500g \cdot f, \text{ for } 10 \pm 1 \sec$.Bending StrengthCapacitance change : within ±12.5%Bending to the limit (1mm) with 1.0mm/sec.SolderabilityMore than 75% of terminal surface is to be soldered newlySnAg3.0Cu0.5 solder $245\pm5°C, 3\pm0.3sec.$. (preheating : 80~120°C for 10~30sec.)Resistance to Soldering HeatCapacitance change : within ±7.5%Solder pot : 270±5°C, 10±1sec.Vibration Test ResistanceCapacitance change : within ±12.5% Tan δ , IR : initial spec.Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)Moisture ResistanceCapacitance change : within ±12.5% Tan δ : 0.05 max IR : 500Mohm or 25Mohm × μ^{E} Whichever is smallerWith 200% of the rated voltage Max. operating temperature 1000+48/-0hrsHigh Temperature ResistanceCapacitance change : within $\pm12.5\%$ Tan δ : 0.05 max IR : 1,000Mohm or 50Mohm × μ^{E} Whichever is smallerWith 200% of the rated voltage Max. operating temperature 1000+48/-0hrsTemperature Capacitance change : within $\pm7.5\%$ 1 cycle condition Min. operating temperature $\rightarrow 25^{\circ}C$	Insulation	10,000Mohm or 500Mohm× <i>μ</i> F	Rated Voltage 60~120 sec.
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Whichever is smaller Whichever is smaller Temperature Capacitance change : within ±7.5% 1 cycle condition Cycling Tan δ, IR : initial spec. Min. operating temperature → 25°C	Resistance		-
Temperature CyclingCapacitance change : Tan δ , IR : initial spec.within $\pm 7.5\%$ Min. operating temperature1 cycle condition Min. operating temperature		IR : 1,000Mohm or 50Mohm × <i>μ</i> F	1000+48/-0hrs
CyclingTan δ , IR : initial spec.Min. operating temperature \rightarrow 25°C		Whichever is smaller	
CyclingTan δ , IR : initial spec.Min. operating temperature \rightarrow 25°C	Temperature	Capacitance change : within ±7.5%	1 cycle condition
\rightarrow Max. operating temperature \rightarrow 25°C	-	Tan δ, IR : initial spec.	-
	-		\rightarrow Max. operating temperature \rightarrow 25°C
5 cycle test			5 cycle test

X The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

- Disclaimer & Limitation of Use and Application -

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury. We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- *④ Military equipment*
- *⑤* Disaster prevention/crime prevention equipment
- *ⓐ* Any other applications with the same as or similar complexity or reliability to the applications set forth above.